

MATERIAL DATA SHEET



SMD Diodes Specialist

Material #	CXXB SERIES	
Product Line	SMB (DO-214AA)	
Date	2009/10/5	
Rev. date	B	

No.	Construction element	Material group	Material weight (mg)	Material	CAS if applicable	Average mass (%)	Sum(%)	Traces
1	Die Chip	Silicon chip	2.82	Silicon	7440-21-3	>99%	0.0286	
				other	-	<1%		
2	Solder	Pb/Sn/Ag	2.904	Pb	7439-92-1	92.50%	0.0295	
				Sn	7440-31-5	5%		
				Ag	7440-22-4	2.50%		
3	Mold Compound	Epoxy Resin	59.67	Silica (SiO2)	14808-60-7	60-90%	0.61	
				Epoxy resin	29690-82-2	10-30%		
				Phenolic resin	9003-35-4	5-20%		
				Antimony trioxide	1309-64-4	0-5%		
				Brominated epoxy resin	40039-93-8	0-5%		
				Carbon Black	1333-86-4	0-1%		
4	Plating	Plating of Sn	0.99	Sn	7440-31-5	>97%	0.01	
				other	-	<3%		
5	Lead frame	Cu	32.059	Cu	7440-50-8	>99%	0.33	
				other	-	<1%		
		Total weight	98.443					